

Electronic Patent Application Fee Transmittal

Application Number:	10083756			
Filing Date:	25-Feb-2002			
Title of Invention:	METHOD FOR FORMING LAYER FOR TRENCH ISOLATION STRUCTURE			
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Filer:	Hosoon Lee/Stormi Davis			
Attorney Docket Number:	4591-227			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
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Total in USD (\$)				1740